TEXAS INSTRUMENTS
Data sheet acquired from Harris Semiconductor
SCHS065C – Revised November 2004

CD4098B Types

CMOS Dual Monostable Multivibrator

High-Voltage Types (20-Volt Rating)

■ CD4098B dual monostable multivibrator provides stable retriggerable/resettable one-shot operation for any fixed-voltage timing application.

An external resistor (R_X) and an external capacitor (C_X) control the timing for the circuit. Adjustment of R_X and C_X provides a wide range of output pulse widths from the Q and $\overline{Q}$ terminals. The time delay from trigger input to output transition (trigger propagation delay) and the time delay from reset input to output transition (reset propagation delay) are independent of R_X and C_X.

Leading-edge-triggering (+TR) and trailing-edge-triggering (−TR) inputs are provided for triggering from either edge of an input pulse. An unused +TR input should be tied to V_{SS}. An unused −TR input should be tied to V_{DD}. A RESET (on low level) is provided for immediate termination of the output pulse or to prevent output pulses when power is turned on. An unused RESET input should be tied to V_{DD}. However, if an entire section of the CD4098B is not used, its RESET should be tied to V_{SS}. See Table I.

In normal operation the circuit triggers (extends the output pulse one period) on the application of each new trigger pulse. For operation in the non-retriggerable mode, $\overline{Q}$ is connected to −TR when leading-edge triggering (+TR) is used or Q is connected to +TR when trailing-edge triggering (−TR) is used.

The time period (T) for this multivibrator can be approximated by: $T_X = \frac{1}{2} R_X C_X$ for $C_X \geq 0.01\ \mu F$. Time periods as a function of R_X for values of C_X and V_{DD} are given in Fig. 8. Values of T vary from unit to unit and as a function of voltage, temperature, and $R_X C_X$.

The minimum value of external resistance, R_X, is 5 kΩ. The maximum value of external capacitance, C_X, is 100 μF. Fig. 9 shows time periods as a function of C_X for values of R_X and V_{DD}.

The output pulse width has variations of ±2.5% typically, over the temperature range of −55°C to 125°C for C_X=1000 pF and R_X=100 kΩ.

For power supply variations of ±5%, the output pulse width has variations of ±0.5% typically, for V_{DD}=10 V and 15 V and ±1% typically, for V_{DD}=5 V at C_X=1000 pF and R_X=5 kΩ.

These types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, and MT suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

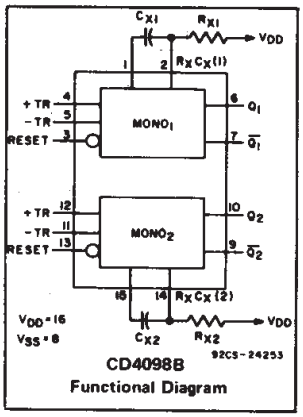
The CD4098B is similar to type MC14528.

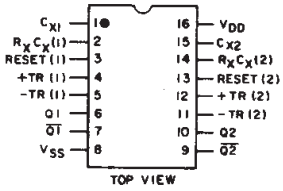
Features:

- **Retriggerable/resettable capability**
- **Trigger and reset propagation delays independent of R_X, C_X**
- **Triggering from leading or trailing edge**
- **Q and $\overline{Q}$ buffered outputs available**
- **Separate resets**
- **Wide range of output-pulse widths**
- **100% tested for maximum quiescent current at 20 V**
- **Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C**
- **Noise margin (full package-temperature range): 1 V at V_{DD}= 5 V; 2 V at V_{DD}=10 V; 2.5 V at V_{DD}=15 V**
- **5-V, 10-V, and 15-V parametric ratings**
- **Standardized, symmetrical output characteristics**
- **Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices."**

Applications:

- **Pulse delay and timing**
- **Pulse shaping**
- **Astable multivibrator**





TERMINAL ASSIGNMENT

MAXIMUM RATINGS, *Absolute-Maximum Values:*

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
Voltages referenced to V_{SS} Terminal) ..... −0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS ..... −0.5V to V_{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT ..... ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
For T_A = −55°C to +100°C 500mW
For T_A = +100°C to +125°C ..... Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW
OPERATING-TEMPERATURE RANGE (T_A) ..... −55°C to +125°C
STORAGE TEMPERATURE RANGE (T_{stg}) ..... −65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max ..... +265°C

RECOMMENDED OPERATING CONDITIONS
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	V_{DD} V	LIMITS MIN.	LIMITS MAX.	UNITS
Supply-Voltage Range (For T_A = Full Package-Temperature Range)	–	3	18	V
Trigger Pulse Width t_W(TR)	5 10 15	140 60 40	– – –	ns
Reset Pulse Width t_W(R) (This is a function of C_X)	–	See Dynamic Char. Chart and Fig. 10		–
Trigger Rise or Fall Time t_r(TR), t_f(TR)	5 - 15	–	100	μs

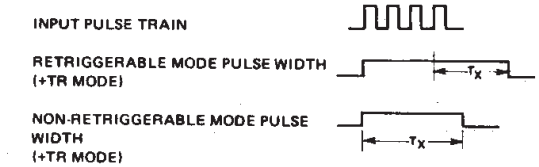
TABLE I

CD4098B FUNCTIONAL TERMINAL CONNECTIONS

FUNCTION	V_{DD} TO TERM. NO.		V_{SS} TO TERM. NO.		INPUT PULSE TO TERM. NO.		OTHER CONNECTIONS	
	$MONO_1$	$MONO_2$	$MONO_1$	$MONO_2$	$MONO_1$	$MONO_2$	$MONO_1$	$MONO_2$
Leading-Edge Trigger/ Retriggerable	3, 5	11, 13			4	12		
Leading-Edge Trigger/ Non-retriggerable	3	13			4	12	5-7	11-9
Trailing-Edge Trigger/ Retriggerable	3	13	4	12	5	11		
Trailing-Edge Trigger/ Non-retriggerable	3	13			5	11	4-6	12-10
Unused Section	5	11	3, 4	12, 13				

NOTES:

1. A RETRIGGERABLE ONE-SHOT MULTIVIBRATOR HAS AN OUTPUT PULSE WIDTH WHICH IS EXTENDED ONE FULL TIME PERIOD (T_X) AFTER APPLICATION OF THE LAST TRIGGER PULSE.
   The minimum time between retriggering edges (or trigger and retrigger edges) is 40 per cent of (T_X).
2. A NON-RETRIGGERABLE ONE-SHOT MULTIVIBRATOR HAS A TIME PERIOD T_X REFERENCED FROM THE APPLICATION OF THE FIRST TRIGGER PULSE.



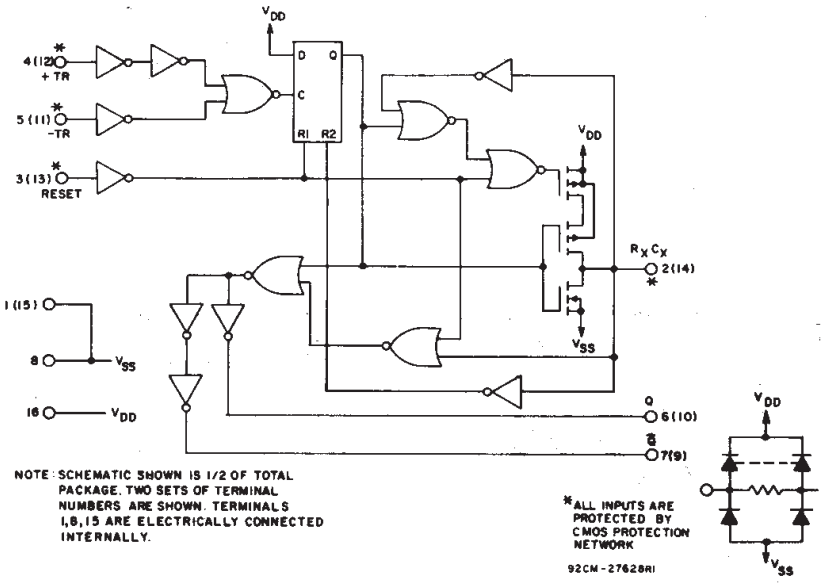


Fig. 4 – CD4098B logic diagram.

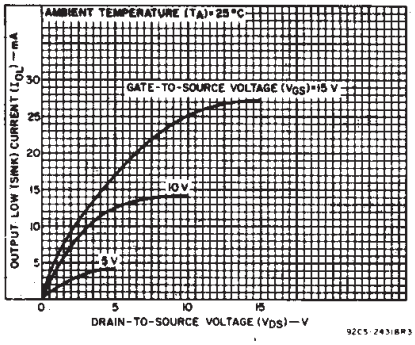


Fig. 1 – Typical output low (sink) current characteristics.

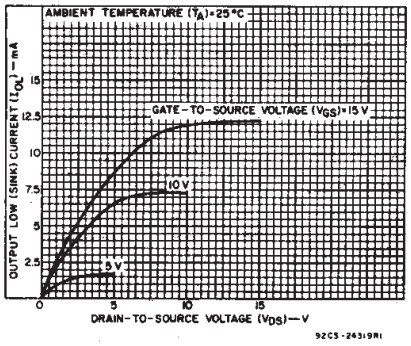


Fig. 2 – Minimum output low (sink) current characteristics.

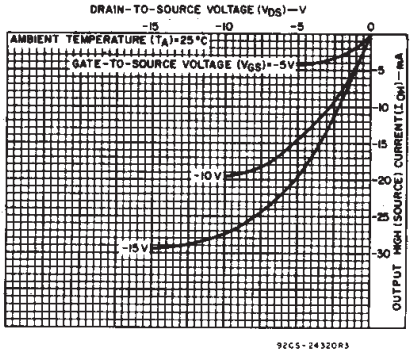


Fig. 3 – Typical output high (source) current characteristics.

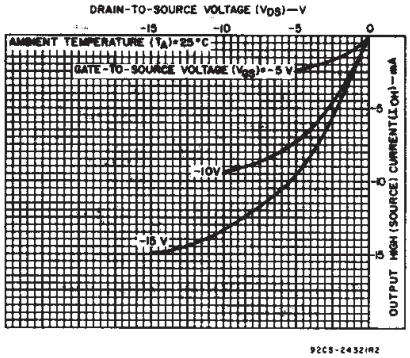


Fig. 5 – Minimum output high (source) current characteristics.

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS V_O (V)	V_{IN} (V)	V_{DD} (V)	LIMITS AT INDICATED TEMPERATURES (°C) −55	−40	+85	+125	+25 Min.	+25 Typ.	+25 Max.	UNITS
Quiescent Device Current I_{DD} Max.	–	0,5	5	1	1	30	30	–	0.02	1	μA
	–	0,10	10	2	2	60	60	–	0.02	2	
	–	0,15	15	4	4	120	120	–	0.02	4	
	–	0,20	20	20	20	600	600	–	0.04	20	
Output Low (Sink) Current, I_{OL} Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	–	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	–	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	–	
Output High (Source) Current, I_{OH} Min.	4.6	0,5	5	−0.64	−0.61	−0.42	−0.36	−0.51	−1	–	
	2.5	0,5	5	−2	−1.8	−1.3	−1.15	−1.6	−3.2	–	
	9.5	0,10	10	−1.6	−1.5	−1.1	−0.9	−1.3	−2.6	–	
	13.5	0,15	15	−4.2	−4	−2.8	−2.4	−3.4	−6.8	–	
Output Voltage: Low-Level, V_{OL} Max.	–	0,5	5	0.05				–	0	0.05	V
	–	0,10	10	0.05				–	0	0.05	
	–	0,15	15	0.05				–	0	0.05	
Output Voltage: High-Level, V_{OH} Min.	–	0,5	5	4.95				4.95	5	–	
	–	0,10	10	9.95				9.95	10	–	
	–	0,15	15	14.95				14.95	15	–	
Input Low Voltage, V_{IL} Max.	0.5,4.5	–	5	1.5				–	–	1.5	V
	1,9	–	10	3				–	–	3	
	1.5,13.5	–	15	4				–	–	4	
Input High Voltage, V_{IH} Min.	0.5,4.5	–	5	3.5				3.5	–	–	
	1,9	–	10	7				7	–	–	
	1.5,13.5	–	15	11				11	–	–	
Input Current, I_{IN} Max.	–	0,18	18	±0.1	±0.1	±1	±1	–	$\pm 10^{-5}$	±0.1	μA

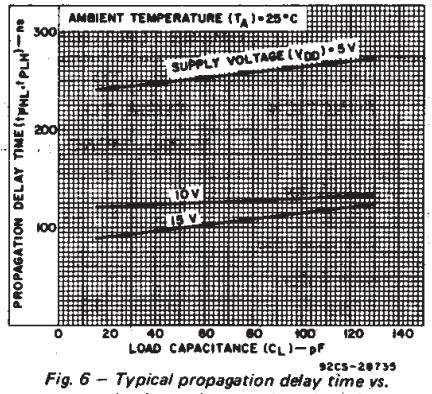


Fig. 6 – Typical propagation delay time vs. load capacitance, trigger into Q out. (All values of C_X and R_X.)

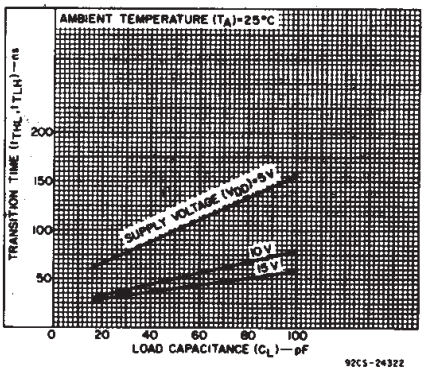


Fig. 7 – Transition time vs. load capacitance for R_X = 5 kΩ-10000 kΩ and C_X = 15 pF-10000 pF.

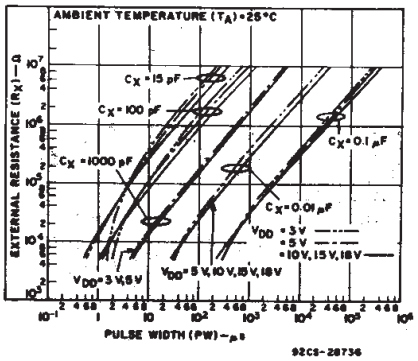


Fig. 8 – Typical external resistance vs. pulse width.

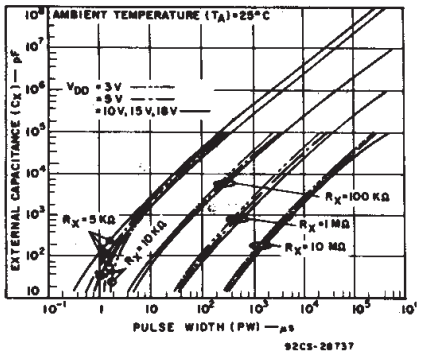


Fig. 9 – Typical external capacitance vs. pulse width.

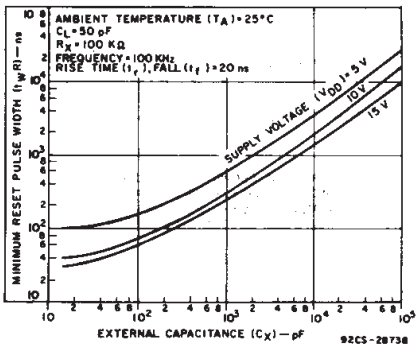


Fig. 10 – Typical minimum reset pulse width vs. external capacitance.

DYNAMIC ELECTRICAL CHARACTERISTICS

At T_A = 25°C; Input t_r,t_f=20 ns, C_L=50 pF, R_L=200 kΩ

CHARACTERISTIC	TEST CONDITIONS			LIMITS		UNITS
	R_X (kΩ)	C_X (pF)	V_{DD} (V)	Typ.	Max.	
Trigger Propagation Delay Time +TR, −TR to Q, $\overline{Q}$ t_{PHL}, t_{PLH}	5 to 10,000	⩾15	5	250	500	ns
			10	125	250	
			15	100	200	
Minimum Trigger Pulse Width, t_{WH}, t_{WL}	5 to 10,000	⩾15	5	70	140	ns
			10	30	60	
			15	20	40	
Transition Time, t_{TLH}	5 to 10,000	⩾15	5	100	200	ns
			10	50	100	
			15	40	80	
t_{THL}	5 to 10,000	15 to 10,000	5	100	200	
			10	50	100	
			15	40	80	
	5 to 10,000	0.01 μF to 0.1 μF	5	150	300	
			10	75	150	
			15	65	130	
	5 to 10,000	0.1 μF to 1 μF	5	250	500	
			10	150	300	
			15	80	160	
Reset Propagation Delay Time, T_{PHL}, T_{PLH}	5 to 10,000	⩾15	5	225	450	ns
			10	125	250	
			15	75	150	
Minimum Reset Pulse Width, t_WR	100	15	5	100	200	ns
			10	40	80	
			15	30	60	
		1000	5	600	1200	
			10	300	600	
			15	250	500	
		0.1 μF	5	25	50	μs
			10	15	30	
			15	10	20	
Trigger Rise or Fall Time t_r(TR), t_f(TR)	–	–	5 to 15	–	100	μs
Pulse Width Match Between Circuits in Same Package	10	10,000	5	5	10	%
			10	7.5	15	
			15	7.5	15	
Input Capacitance, C_{IN}	Any Input			5	7.5	pF

TEST CIRCUITS

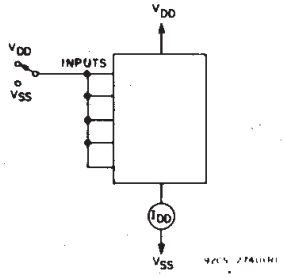


Fig. 12 – Quiescent-device-current test circuits.

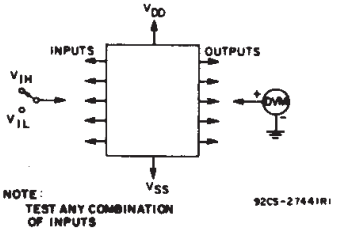


Fig. 13 – Input-voltage test circuit.

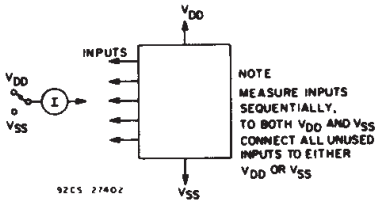


Fig. 14 – Input leakage current test circuit.

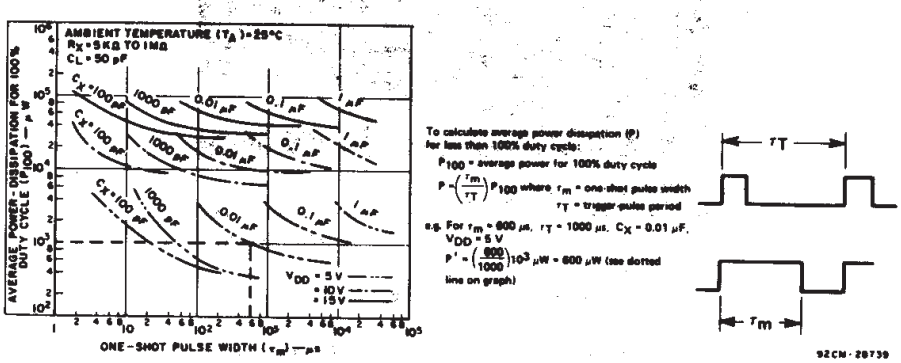


Fig. 11 – Average power dissipation vs. one-shot pulse width.

APPLICATIONS

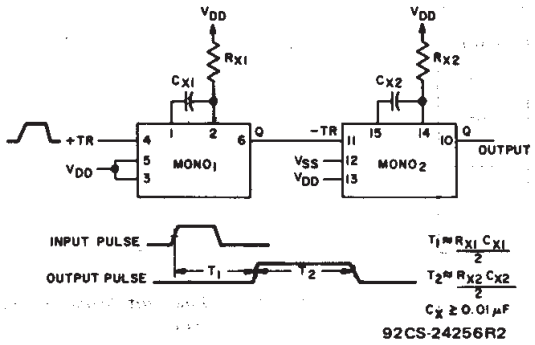


Fig. 15 – Pulse delay.

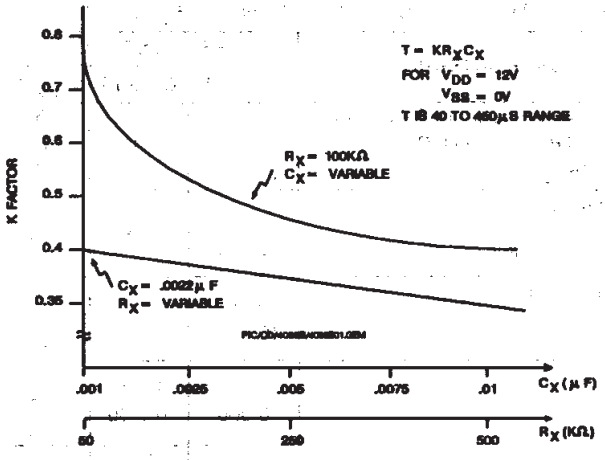


Fig. 17 – K-Factor for V_{DD} = 12V.

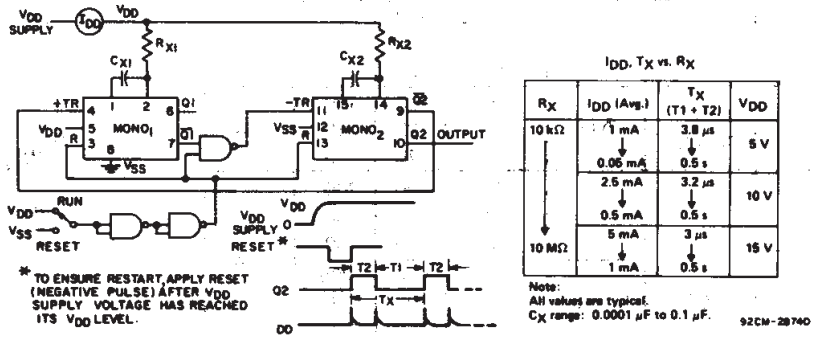
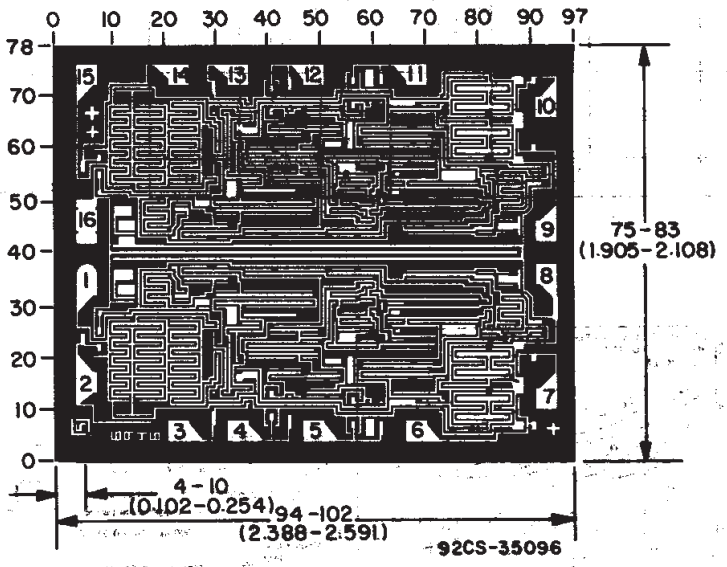


Fig. 16 – Astable multivibrator with restart after reset capability.



Dimensions and Pad Layout for CD4098BH

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
CD4098BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4098BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4098BF	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD4098BF3A	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD4098BFB	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD4098BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BM96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4098BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
JM38510/17504BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements

for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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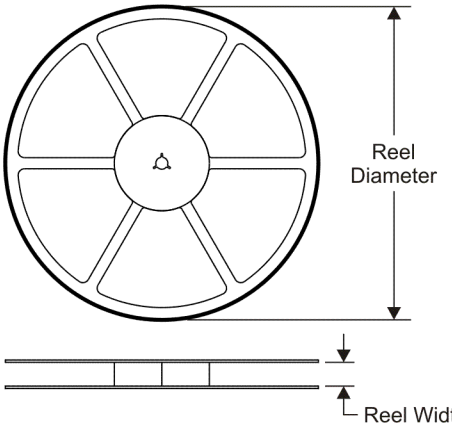
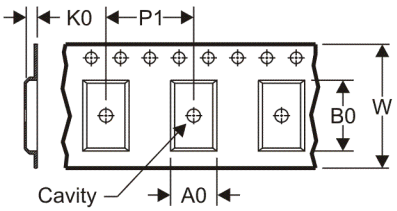
TAPE AND REEL INFORMATION

REEL DIMENSIONS

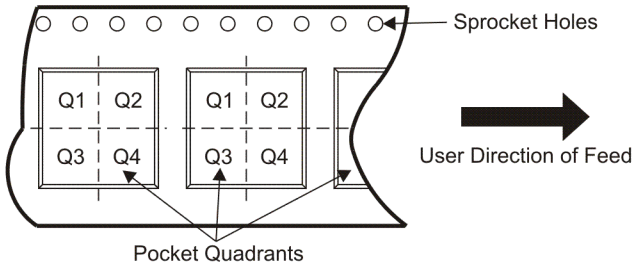


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

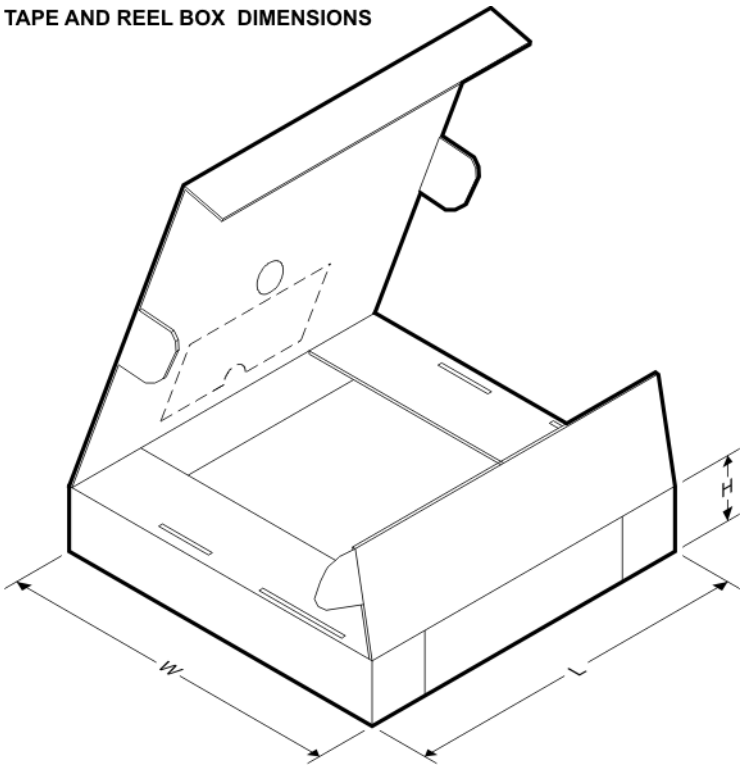
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4098BM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD4098BPWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

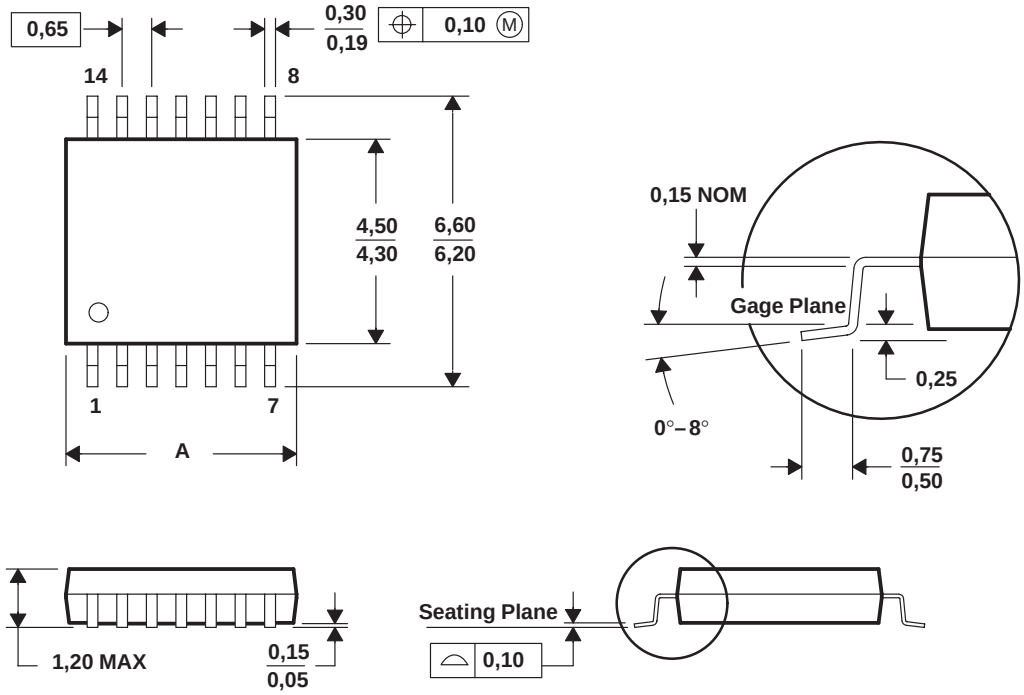


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4098BM96	SOIC	D	16	2500	333.2	345.9	28.6
CD4098BPWR	TSSOP	PW	16	2000	346.0	346.0	29.0

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

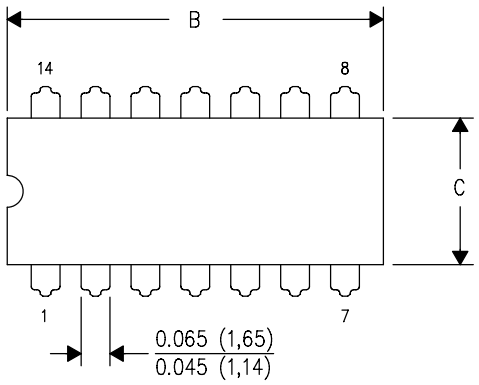
4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

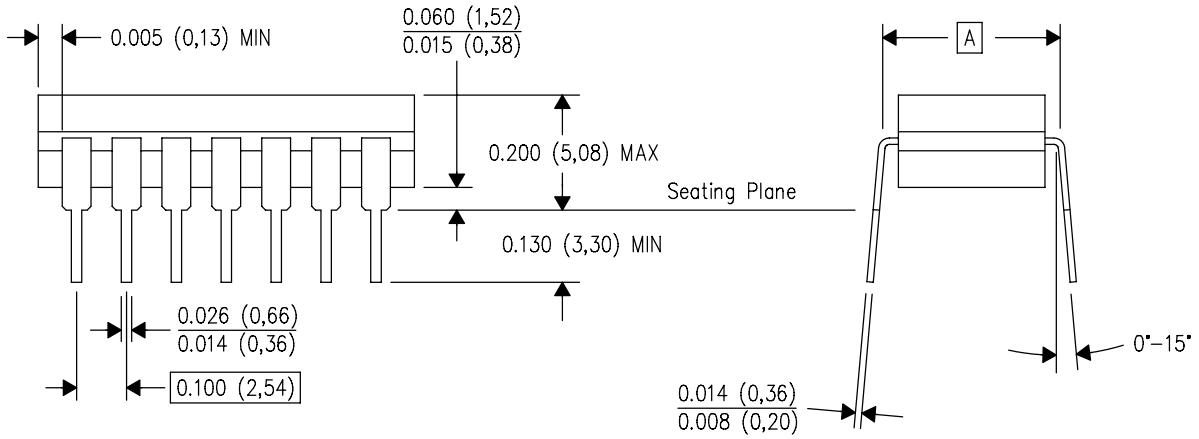
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



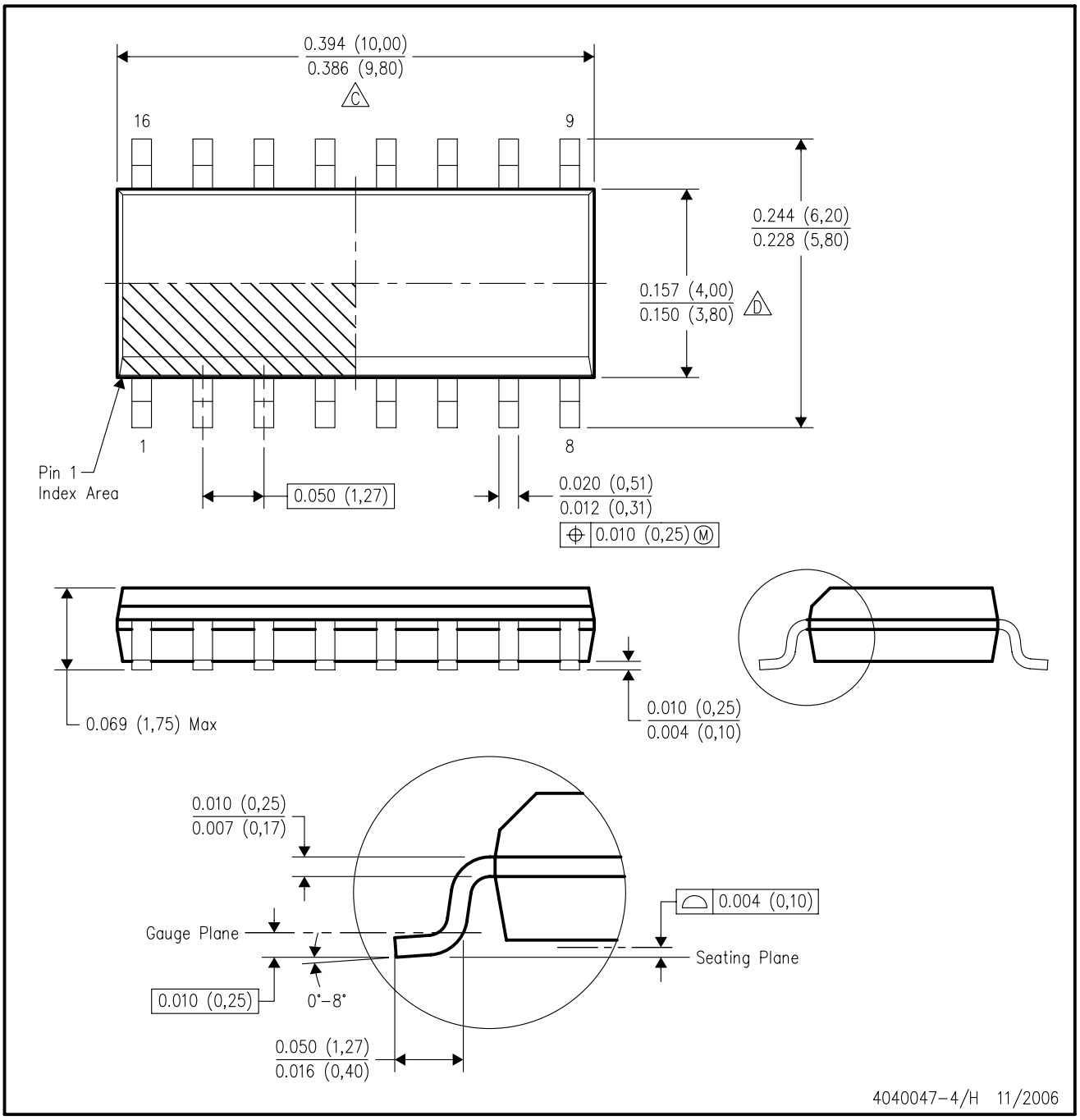
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

D (R–PDSO–G16) PLASTIC SMALL–OUTLINE PACKAGE

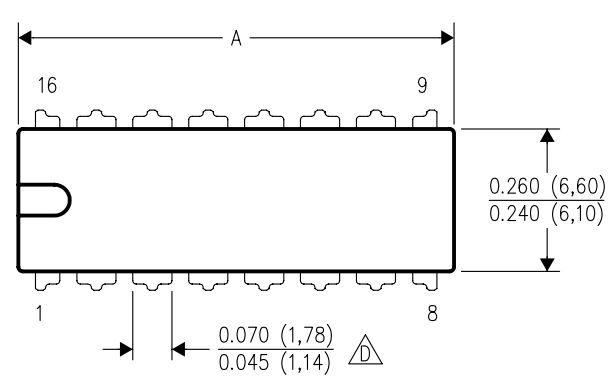


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AC.

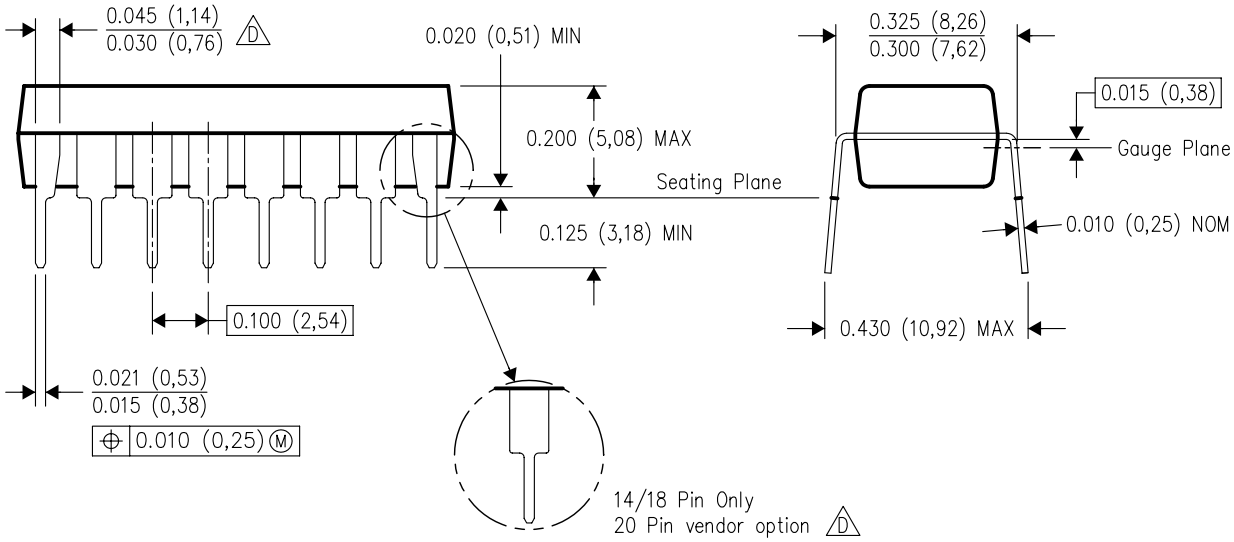
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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